30V Nch+Nch Middle Power MOSFET

V _{DSS}	30V
R _{DS(on)} (Max.)	42mΩ
I _D	±5.5A
P _D	2W

Features

- 1) Low on resistance.
- 2) Small Surface Mount Package .
- 3) Pb-free lead plating; RoHS compliant.
- 4) Halogen Free.

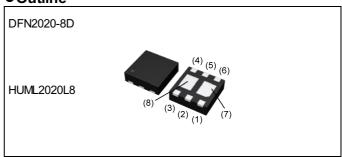
Application

Load Switch

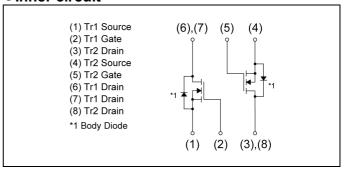
Battery Switch for mobile

DC/DC Converter

Outline



•Inner circuit



Packaging specifications

<u> </u>	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TCR
	Marking	K03

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	30	V
Continuous drain current	I _D	±5.5	А
Pulsed drain current	I _{DP} *1	±12	А
Gate - Source voltage	V _{GSS}	±12	V
Avalanche current, single pulse	I _{AS} *2	5.5	Α
Avalanche energy, single pulse	E _{AS} *2	2.4	mJ
Power dissipation	P _D *3	2	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Cymahal	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R _{thJA} *3	1	-	62.5	°C/W

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Damanatan	0	0 - 1141 - 11 -	Values			1.1:4	
Parameter	Symbol	Conditions	Min.	Тур. Мах.		Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA		-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	18	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V		-	1	μA	
Gate - Source leakage current	I _{GSS}	$V_{DS} = 0V, V_{GS} = \pm 12V$	1	-	±100	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 1mA$	0.5	-	1.5	V	
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{\text{GS(th)}}}{\DeltaT_j}$	I _D = 1mA referenced to 25°C	-	-1.8	-	mV/°C	
Static drain - source	D *4	V _{GS} = 4.5V, I _D = 5.0A	-	30	42	m0	
on - state resistance	R _{DS(on)} *4	V _{GS} = 2.5V, I _D = 2.75A	-	45	63	mΩ	
Gate resistance	R_G	f=1MHz, open drain	ı	2.2	-	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 5.0V, I _D = 5.0A	2.3	-	-	S	

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} L \simeq 0.1mH, V_{DD} = 15V, R_G = 25 Ω , STARTING T $_{j}$ = 25 $^{\circ}$ C Fig.3-1,3-2

^{*3} Mounted on a Cu boad (40×40×0.8mm)

^{*4} Pulsed

●Electrical characteristics (T_a = 25°C) <Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Offic	
Input capacitance	C _{iss}	V _{GS} = 0V	-	450	-		
Output capacitance	C _{oss}	V _{DS} = 15V	-	50	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	35	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 15V, V_{GS} = 4.5V$	-	7.2	-		
Rise time	t _r *4	I _D = 2.75A	-	5.8	-		
Turn - off delay time	t _{d(off)} *4	$R_L = 6\Omega$	-	13	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	5.1	-		

● Gate charge characteristics (T_a = 25°C) < Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit
raianietei	Symbol	Conditions	Min.	Тур.	Max.	Uriit
Total gate charge	Q_g^{*4}		-	4.0	-	
Gate - Source charge	Q _{gs} *4	$V_{DD} \approx 15V, I_{D} = 5.5A$ $V_{GS} = 4.5V$	-	1.0	-	nC
Gate - Drain charge	Q _{gd} *4	V GS - 4.5 V	-	1.0	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit
raianetei	Symbol Conditions -		Min.	Тур.	Max.	Offic
Continuous forward current	I _S	T _a = 25°C	-	-	1.6	А
Pulse forward current	I _{SP} *1		-	-	12	
Forward voltage	V_{SD}^{*4}	$V_{GS} = 0V, I_{S} = 1.6A$	-	ı	1.2	V

Fig.1 Power Dissipation Derating Curve

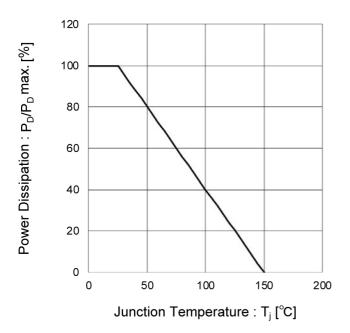
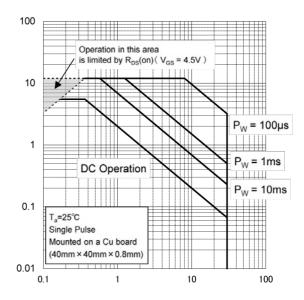


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

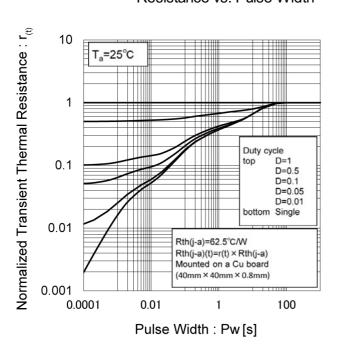
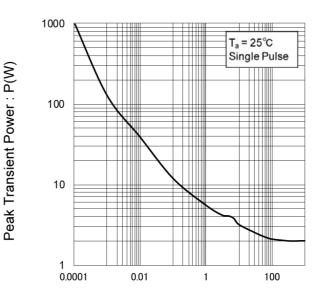


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: Pw[s]

Fig.5 Typical Output Characteristics(I)

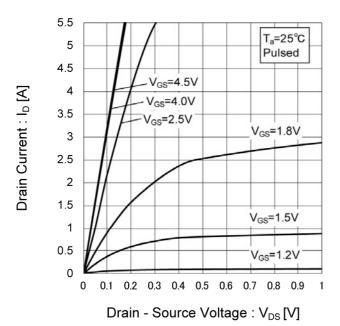
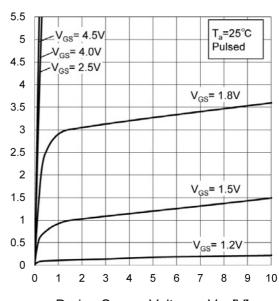


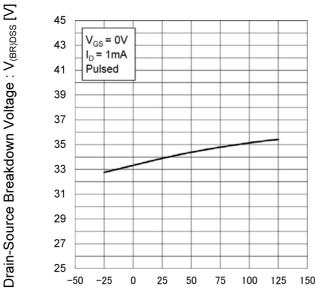
Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

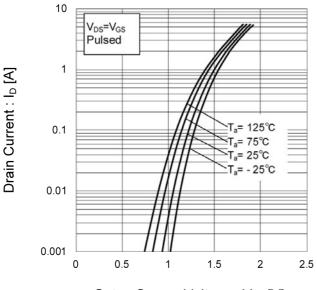
Fig.7 Breakdown Voltage vs. Junction Temperature



150

Junction Temperature : T_i [°C]

Fig.8 Typical Transfer Characteristics



Gate - Source Voltage : V_{GS} [V]

Fig.9 Gate Threshold Voltage vs. Junction Temperature

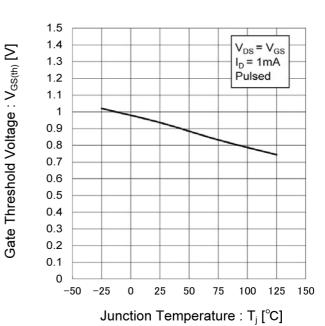
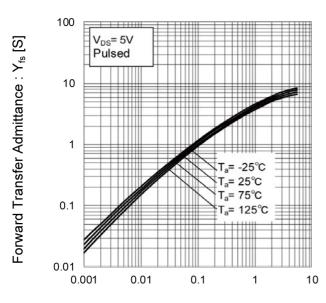


Fig.10 Forward Transfer Admittance vs. Drain Current



Drain Current: ID [A]

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Fig.11 Drain Current Derating Curve

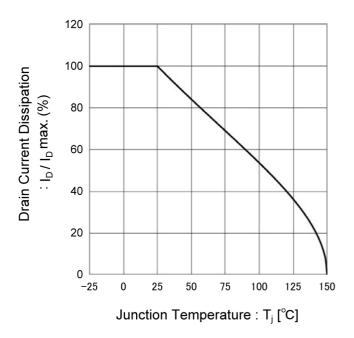


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

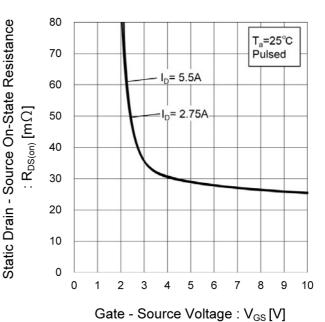
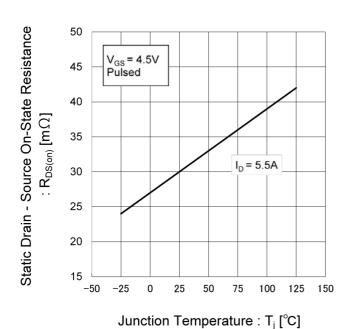


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



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Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

Static Drain Current : I_D [A]

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

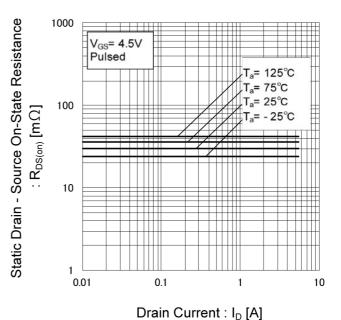
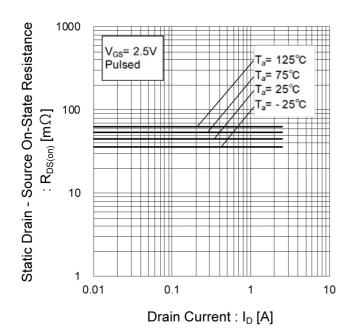


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)



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Fig.17 Typical Capacitance vs. Drain - Source Voltage

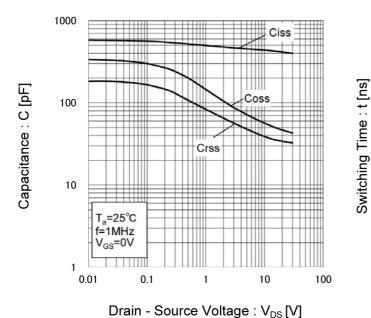
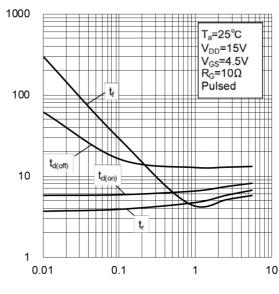


Fig.18 Switching Characteristics

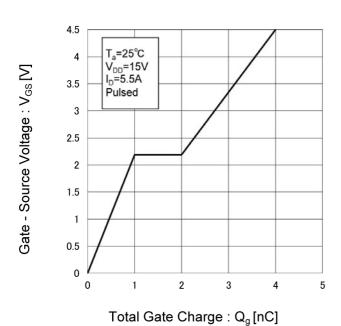


Drain Current : I_D [A]

Fig.20 Source Current vs. Source Drain

Voltage

Fig.19 Dynamic Input Characteristics



Source Current :I_S [A]

10 V_{GS}=0V Pulsed

1 T_a= 125°C T_a= 75°C T_a= -25°C T_a= -25

Source-Drain Voltage: V_{SD}[V]

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

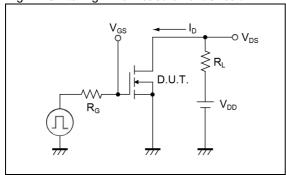


Fig.2-1 Gate Charge Measurement Circuit

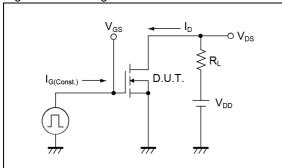


Fig.3-1 Avalanche Measurement Circuit

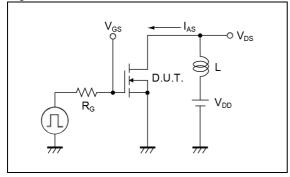


Fig.1-2 Switching Waveforms

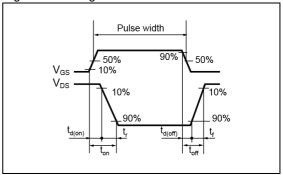


Fig.2-2 Gate Charge Waveform

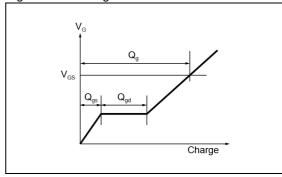
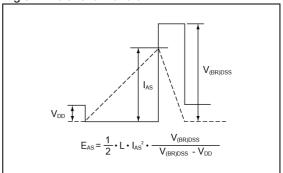


Fig.3-2 Avalanche Waveform

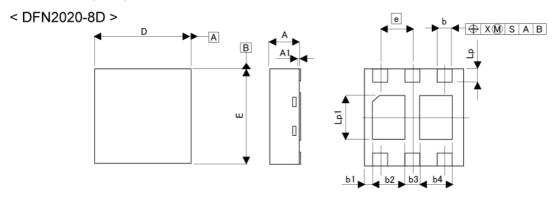


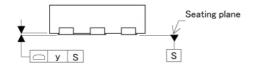
Notice

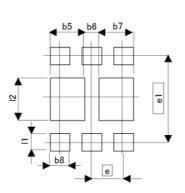
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions

HUML2020L8 (Dual)







Pattern of terminal position areas [Not a pattern of soldering pads]

	MILIMETERS INCHES						
DIM	IVIILIIVIE	TERS	INC	HES			
DIIVI	MIN	MAX	MIN	MAX			
Α	0.55	0.65	0.022	0.026			
A1	0.00	0.05	0.000	0.002			
b	0.25	0.35	0.010	0.014			
b1	0.	25	0.0)10			
b2	0.60	0.70	0.024	0.028			
b3	0	.3	0.0)12			
b4	0.60	0.70	0.024	0.028			
D	1.90	2.10	0.075	0.083			
Е	1.90	2.10	0.075	0.083			
е	0.	65	0.0)26			
Lp	0.225	0.325	0.009	0.013			
Lp1	0.80	1.00	0.031	0.039			
х	-	0.10	E-1	0.004			
у	-	0.10		0.004			

DIM	MILIMETERS		INCHES		
DIIVI	MIN	MAX	MIN	MAX	
b5	-	0.70	-	0.028	
b6	0.20	0.30	0.008	0.012	
b7	-	0.70	-	0.028	
b8	-	0.45	-	0.018	
e1	1.7	725	0.0)68	
l1 -		0.425	9.5	0.017	
12	-	1.00	-	0.039	

Dimension in mm/inches



Notice

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Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГУООШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
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- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный) Email: org@lifeelectronics.ru